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捷多邦,专业PSN54ABT.2952AppSN74ABT2952A OCTAL BUS TRANSCEIVERS AND REGISTERS WITH 3-STATE OUTPUTS

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- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Two 8-Bit Back-to-Back Registers Store **Data Flowing in Both Directions**
- **Noninverting Outputs**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs

description

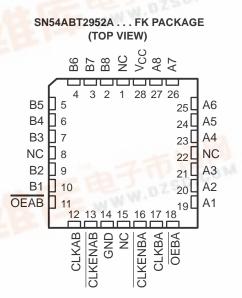
The 'ABT2952A transceivers consist of two 8-bit back-to-back registers that store data flowing in both directions between two bidirectional buses. Data on the A or B bus is stored in the registers on the low-to-high transition of the clock (CLKAB or CLKBA) input provided that the clock-enable (CLKENAB or CLKENBA) input is low. Taking the output-enable (OEAB or OEBA) input low accesses the data on either port.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2952A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT2952A is characterized for operation from -40°C to 85°C.



B2 [7	18] A3
B1 [8	17] A2
OEAB	9] A1
CLKAB [10	15] OEBA
CLKENAB	11] CLKBA
GND [12 📂	13	CLKENBA



NC - No internal connection



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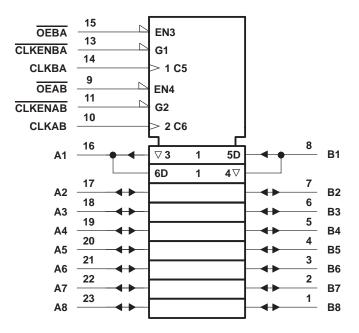
THE R.	OTIO		
FUN		NIA	BLE [†]
	• • • •		

	OUTPUT			
CLKENAB	CLKAB	OEAB	Α	В
Н	Х	L	Х	в ₀ ‡ в ₀ ‡
Х	H or L	L	Х	в ₀ ‡
L	\uparrow	L	L	L
L	\uparrow	L	Н	н
Х	Х	Н	Х	Z

[†] A-to-B data flow is shown; B-to-A data flow is similar, but uses CLKENBA, CLKBA, and OEBA.

Level of B before the indicated steady-state input conditions were established

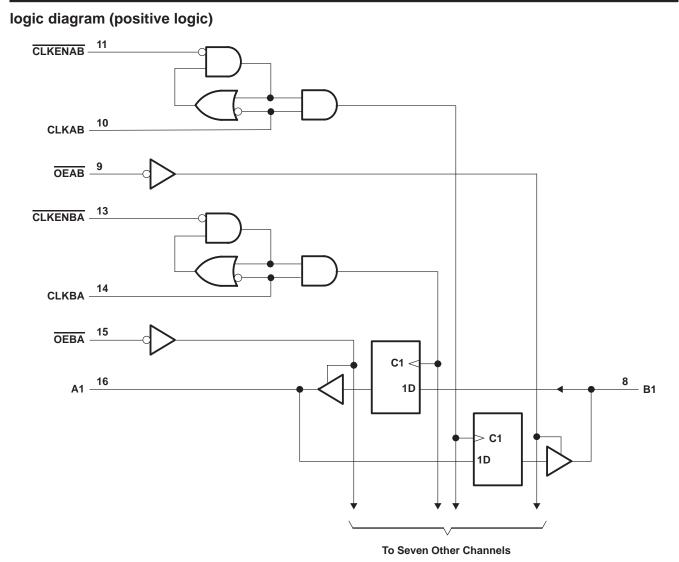
logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



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Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, V_{O}	
Current into any output in the low state, I _O : SN54ABT2952A	
SN74ABT2952A	
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package	104°C/W
DW package	81°C/W
NT package	67°C/W
PW package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT	2952A	SN74ABT2952A		UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC} Supply voltage				5.5	4.5	5.5	V
VIH	VIH High-level input voltage				2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		0	VCC	0	VCC	V
IОН	High-level output current			-24		-32	mA
IOL	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Т _А	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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		TEST CONDITIONS		Т	A = 25°C	;	SN54AB1	F2952A	SN74ABT2952A			
Ρ/	ARAMETER	IESIC	ONDITIONS	MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	l _l = –18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
		V _{CC} = 5 V,	I _{OH} = -3 mA	3			3		3	MAX -1.2 2.5 3 2 0.55 ±1 ±100 50 -50 ±100 50		
Vон			I _{OH} = -24 mA	2			2				V	
		V _{CC} = 4.5 V	I _{OH} = -32 mA	2*					2			
			I _{OL} = 48 mA			0.55		0.55			V mV	
VOL		V _{CC} = 4.5 V	I _{OL} = 64 mA			0.55*				0.55		
V _{hys}			_		100							
	Control inputs		$V_{I} = V_{CC}$ or GND			±1		±1		±1	μA	
ł	A or B ports	V _{CC} = 5.5 V,				±100		±100		±100		
^I оzн [‡]	:	V _{CC} = 5.5 V,	V _O = 2.7 V			50*		10		50	μA	
IOZL [‡]		V _{CC} = 5.5 V,	V _O = 0.5 V			-50*		-10		-50	μA	
loff		V _{CC} = 0,	VI or VO \leq 4.5 V			±100*				±100	μA	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
lO§		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high		1	250		250		250	μA	
ICC	A or B ports	$I_{O} = 0,$	Outputs low		24	35		35		35	mA	
	GND	V _I = V _{CC} or GND	Outputs disabled		0.5	250		250		250	μA	
∆I _{CC} ¶	•	V _{CC} = 5.5 V, Or Other inputs at \				1.5		1.5		1.5	mA	
Ci	Control inputs	VI = 2.5 V or 0.5	V		3.5						pF	
Cio	A or B ports	V _O = 2.5 V or 0.	5 V		7.5						pF	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5$ V.

[‡] The parameters I_{OZH} and I_{OZL} include the input leakage current.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				V _{CC} = 5 V, T _A = 25°C		SN54ABT2952A		SN74ABT2952A		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
fclock	f _{clock} Clock frequency			0	150	0	150	0	150	MHz
tw	W Pulse duration, CLK high or low			3.3		3.3		3.3		ns
L	A or B		Lligh or low	2.5		3		2.5		50
t _{su}	Setup time before CLK [↑]	CLKEN	KEN High or low			3		3		ns
+.	t_h Hold time after CLK [↑]	A or B		1.5		1.5		1.5		-
ⁿ		CLKEN		2		2		2		ns



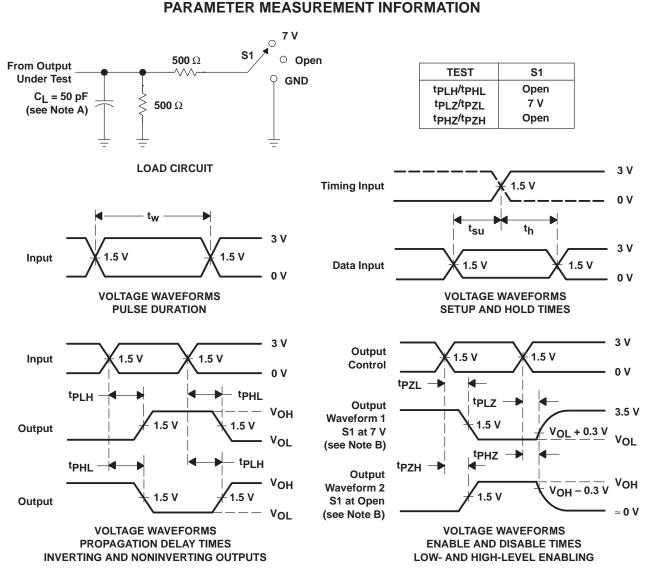
SN54ABT2952A, SN74ABT2952A **OCTAL BUS TRANSCEIVERS AND REGISTERS** WITH 3-STATE OUTPUTS SCBS203D – AUGUST 1992 – REVISED JANUARY 1998

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT2952A		SN74ABT2952A		UNIT
		(001701)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
fmax			150			150		150		MHz
^t PLH	CLKAB or CLKBA	B or A	2	3.3	5.2	2	6.3	2	5.9	ns
^t PHL	CLKAD OF CLKDA		2.5	4	6.1	2.5	6.8	2.5	6.3	
^t PZH		A or B	1.5	3.2	4.7	1.5	5.7	1.5	5.6	ns
^t PZL	OEBA or OEAB	AUB	2	3.7	5.7	2	6.7	2	6.6	115
^t PHZ		A or B	1.5	3.5	5.1	1.5	6.5	1.5	6.4	ns
^t PLZ	OEBA or OEAB	AUB	1.5	3.4	5.9	1.5	6.7	1.5	6.2	115



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NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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